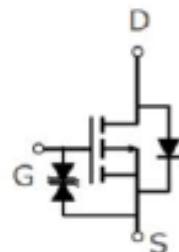
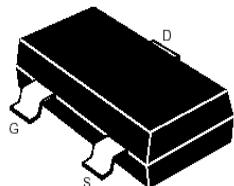


**SOT-23**

$V_{(BR)DSS}$	$R_{DS(on)}$ Typ	I_D Max
-20V	37mΩ @ -4.5V	-4.8A
	43mΩ @ -3.3V	

Features

- Low $R_{DS(on)}$ @ $V_{GS}=-4.5V$
- -3.3V Logic Level Control
- P Channel SOT23 Package
- HMB ESD Protection 2KV
- Pb-Free, RoHS Compliant

Applications

- Load Switch
- Switching circuits
- High-speed line driver
- Power Management Functions

Order Information

Product	Package	Marking	Packing	Min Unit Quantity
BM3415E	SOT23	3415E	3000PCS/Reel	3000PCS

Absolute Maximum Ratings

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating	Unit
Common Ratings (TA=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	±8	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	-20	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-50 to 150	°C
Mounted on Large Heat Sink			
I_{DM}	Pulse Drain Current Tested①	$T_A = 25^\circ C$	-30
I_D	Continuous Drain Current	$T_A = 25^\circ C$	-4.8
		$T_A = 70^\circ C$	-3.6
P_D	Maximum Power Dissipation	$T_A = 25^\circ C$	1.5
		$T_A = 70^\circ C$	1.0
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	80	°C/W



Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ $I_D=-250\mu\text{A}$	-20	--	--	V
I_{DSS}	Zero Gate Voltage Drain Current($T_A=25^\circ\text{C}$)	$V_{\text{DS}}=-20\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	-1	μA
	Zero Gate Voltage Drain Current($T_A=125^\circ\text{C}$)	$V_{\text{DS}}=-16\text{V}$, $V_{\text{GS}}=0\text{V}$	--	--	-100	μA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 8\text{V}$, $V_{\text{DS}}=0\text{V}$	--	--	± 10	μA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=-250\mu\text{A}$	-0.4	-0.7	-1.2	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^②	$V_{\text{GS}}=-4.5\text{V}$, $I_D=-4\text{A}$	--	37	45	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^②	$V_{\text{GS}}=-3.3\text{V}$, $I_D=-3\text{A}$	--	43	55	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance ^②	$V_{\text{GS}}=-2.5\text{V}$, $I_D=-2\text{A}$	--	52	65	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=-10\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	--	675	--	pF
C_{oss}	Output Capacitance		--	120	--	pF
C_{rss}	Reverse Transfer Capacitance		--	85	--	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=-10\text{V}$ $I_D=-4\text{A}$, $V_{\text{GS}}=-4.5\text{V}$	--	14.2	--	nC
Q_{gs}	Gate Source Charge		--	3.2	--	nC
Q_{gd}	Gate Drain Charge		--	5.8	--	nC
Switching Characteristics						
$t_{\text{d(on)}}$	Turn on Delay Time	$V_{\text{DD}}=-10\text{V}$, $I_D=-2\text{A}$, $R_G=3.3\Omega$, $V_{\text{GS}}=-4.5\text{V}$	--	15	--	ns
t_r	Turn on Rise Time		--	11	--	ns
$t_{\text{d(off)}}$	Turn Off Delay Time		-	22	--	ns
t_f	Turn Off Fall Time		--	35	--	ns
Source Drain Diode Characteristics						
I_{SD}	Source drain current(Body Diode)	$T_A=25^\circ\text{C}$	--	--	-2	A
V_{SD}	Forward on voltage ^②	$T_J=25^\circ\text{C}$, $I_{\text{SD}}=-2\text{A}$, $V_{\text{GS}}=0\text{V}$	--	-0.83	-1.2	V

Notes:

① Pulse width limited by maximum allowable junction temperature

②Pulse test ; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.



Typical Characteristics

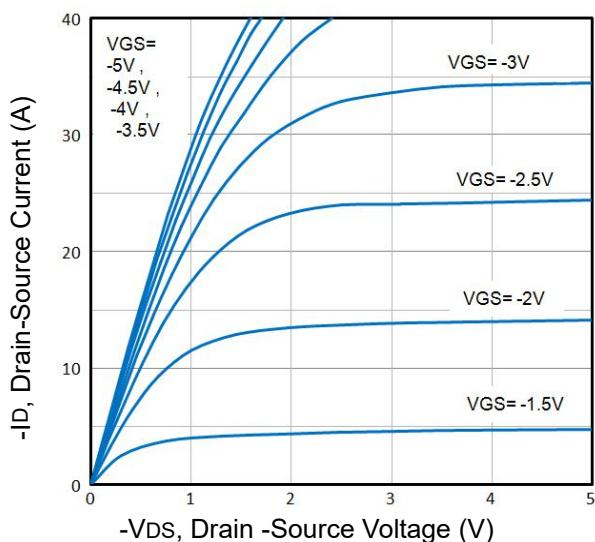


Fig1. Typical Output Characteristics

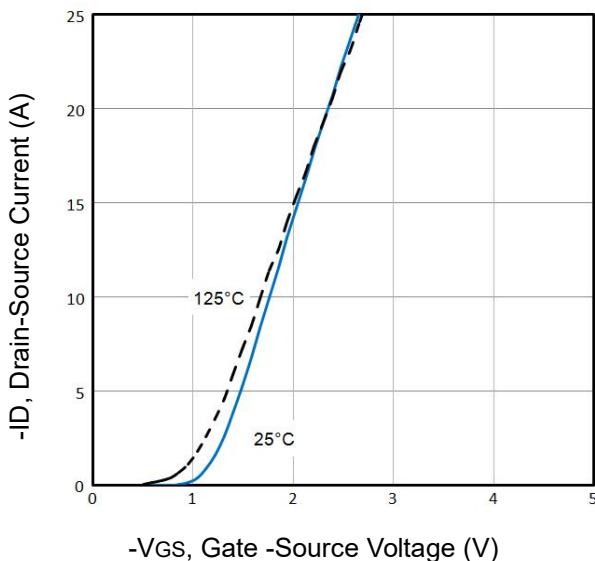


Fig3. Typical Transfer Characteristics

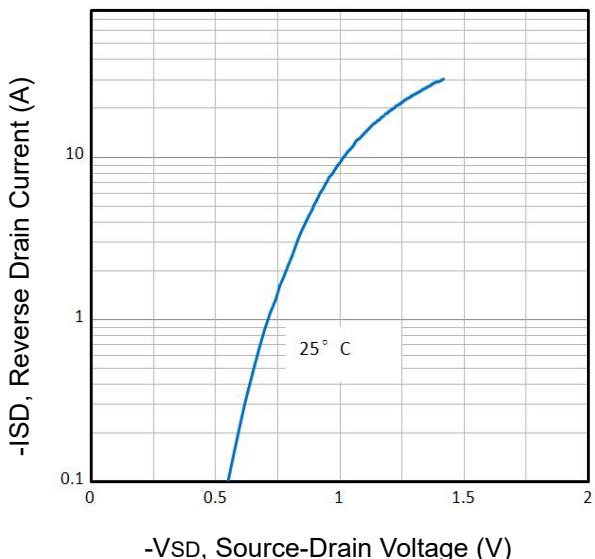


Fig5. Typical Source-Drain Diode Forward Voltage

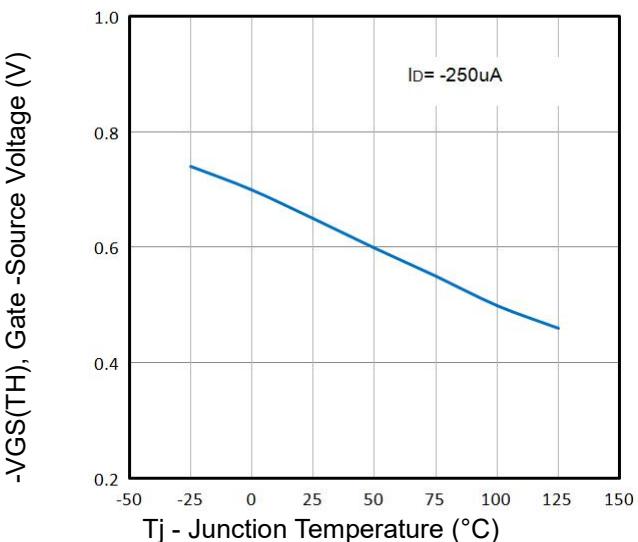


Fig2. Normalized Threshold Voltage Vs. Temperature

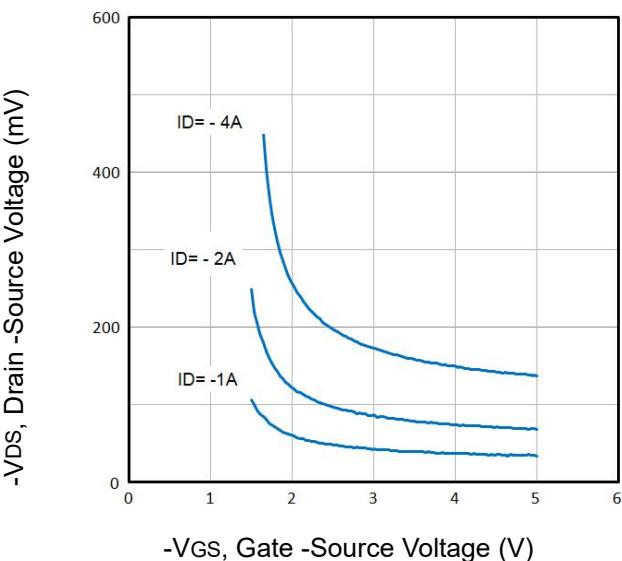


Fig4. Drain -Source Voltage vs Gate -Source Voltage

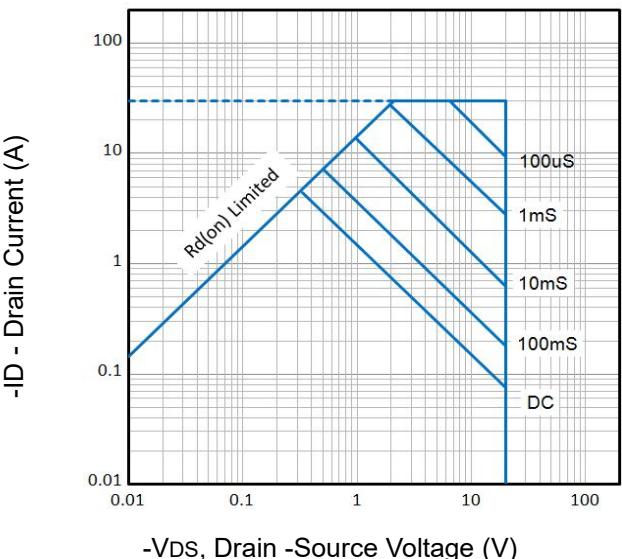


Fig6. Maximum Safe Operating Area



Typical Characteristics

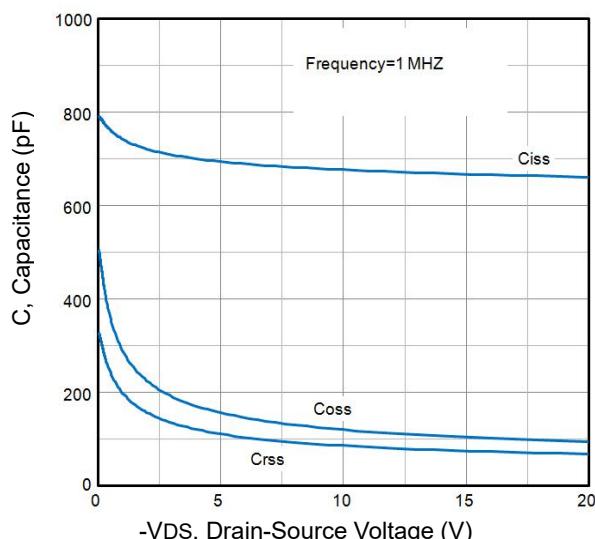


Fig7. Typical Capacitance Vs. Drain-Source Voltage

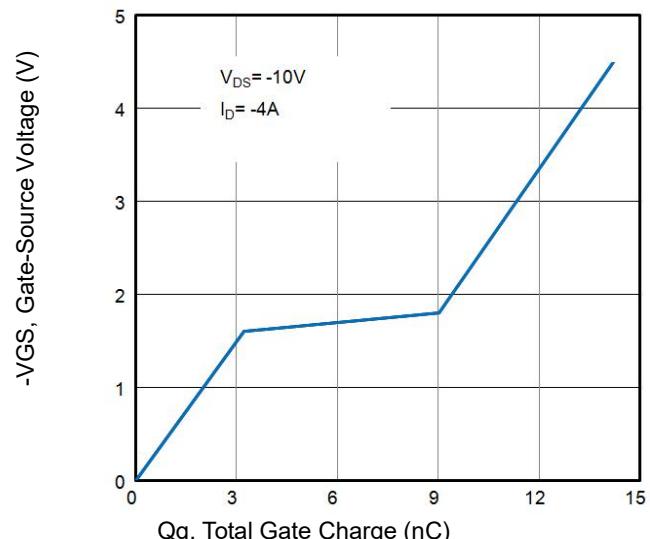


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

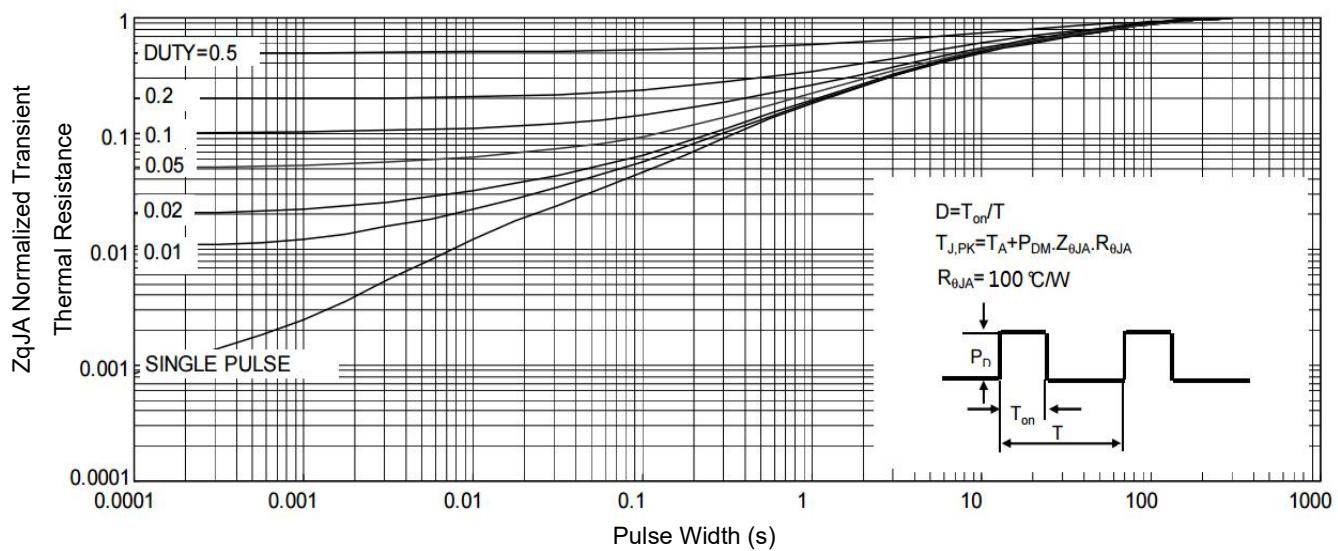


Fig9. Normalized Maximum Transient Thermal Impedance

SOT-23 PACKAGE OUTLINE Plastic surface mounted package

